TE Internal #: 966662-4

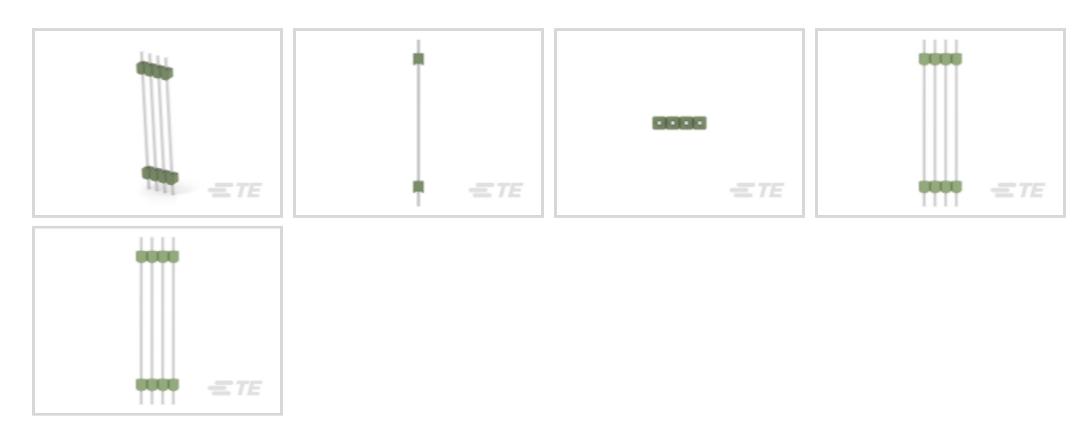
PCB Mount Header, Vertical, Board-to-Board, 4 Position, 2.54mm [.

1in] Centerline, Breakaway, Gold, Printed Circuit Board

View on TE.com >



Connectors > PCB Connectors > Board-to-Board Connectors > Board-to-Board Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical Connector System: Board-to-Board

Number of Positions: 4

Centerline (Pitch): 2.54 mm [.1 in]

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Breakaway
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	

PCB Mount Orientation	Vertical
Number of Positions	4
Board-to-Board Configuration	Parallel

Contact Features

Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	5 A

Termination Features

Termination Method to Printed Circuit Board	Through Hole - Solder	
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Mechanical Attachment

Mating Alignment	Without
PCB Mount Retention	Without
	Without
PCB Mount Alignment	
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	33 mm[1.29 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	

Packaging Method

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JUN 2020 (209) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Box & Carton



Solder Process Capability

Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought

























Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_966662-4_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_966662-4_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_966662-4_A.3d_stp.zip

English

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Agency Approvals

UL Report

English